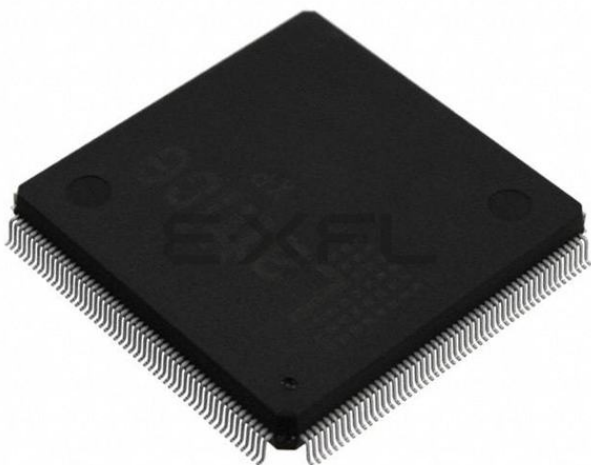




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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	3000
Total RAM Bits	55296
Number of I/O	136
Number of Gates	-
Voltage - Supply	1.71V ~ 3.465V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfxp3c-3q208c

Introduction

The LatticeXP family of FPGA devices combine logic gates, embedded memory and high performance I/Os in a single architecture that is both non-volatile and infinitely reconfigurable to support cost-effective system designs.

The re-programmable non-volatile technology used in the LatticeXP family is the next generation ispXP™ technology. With this technology, expensive external configuration memories are not required and designs are secured from unauthorized read-back. In addition, instant-on capability allows for easy interfacing in many applications.

The ispLEVER® design tool from Lattice allows large complex designs to be efficiently implemented using the LatticeXP family of FPGA devices. Synthesis library support for LatticeXP is available for popular logic synthesis tools. The ispLEVER tool uses the synthesis tool output along with the constraints from its floor planning tools to place and route the design in the LatticeXP device. The ispLEVER tool extracts the timing from the routing and back-annotates it into the design for timing verification.

Lattice provides many pre-designed IP (Intellectual Property) ispLeverCORE™ modules for the LatticeXP family. By using these IPs as standardized blocks, designers are free to concentrate on the unique aspects of their design, increasing their productivity.

Table 2-4. PFU Modes of Operation

Logic	Ripple	RAM ¹	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR16x2 x 4 DPR16x2 x 2	ROM16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR16x4 x 2 DPR16x4 x 1	ROM16x2 x 4
LUT 6x2 or MUX 8x1 x 2	2-bit Counter x 4	SPR16x8 x 1	ROM16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM16x8 x 1

1. These modes are not available in PFF blocks

Routing

There are many resources provided in the LatticeXP devices to route signals individually or as buses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

The inter-PFU connections are made with x1 (spans two PFU), x2 (spans three PFU) and x6 (spans seven PFU). The x1 and x2 connections provide fast and efficient connections in horizontal, vertical and diagonal directions. The x2 and x6 resources are buffered allowing both short and long connections routing between PFUs.

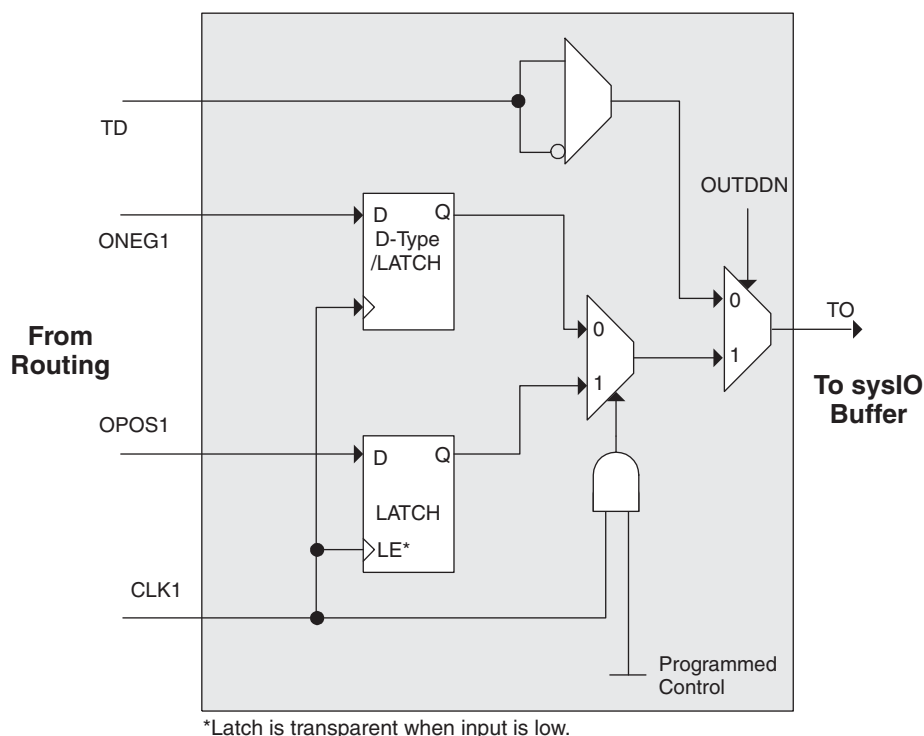
The ispLEVER design tool takes the output of the synthesis tool and places and routes the design. Generally, the place and route tool is completely automatic, although an interactive routing editor is available to optimize the design.

Clock Distribution Network

The clock inputs are selected from external I/O, the sysCLOCK™ PLLs or routing. These clock inputs are fed through the chip via a clock distribution system.

Primary Clock Sources

LatticeXP devices derive clocks from three primary sources: PLL outputs, dedicated clock inputs and routing. LatticeXP devices have two to four sysCLOCK PLLs, located on the left and right sides of the device. There are four dedicated clock inputs, one on each side of the device. Figure 2-5 shows the 20 primary clock sources.

Figure 2-25. Tristate Register Block**Control Logic Block**

The control logic block allows the selection and modification of control signals for use in the PIO block. A clock is selected from one of the clock signals provided from the general purpose routing and a DQS signal provided from the programmable DQS pin. The clock can optionally be inverted.

The clock enable and local reset signals are selected from the routing and optionally inverted. The global tristate signal is passed through this block.

DDR Memory Support

Implementing high performance DDR memory interfaces requires dedicated DDR register structures in the input (for read operations) and in the output (for write operations). As indicated in the PIO Logic section, the LatticeXP devices provide this capability. In addition to these registers, the LatticeXP devices contain two elements to simplify the design of input structures for read operations: the DQS delay block and polarity control logic.

DLL Calibrated DQS Delay Block

Source Synchronous interfaces generally require the input clock to be adjusted in order to correctly capture data at the input register. For most interfaces a PLL is used for this adjustment, however in DDR memories the clock (referred to as DQS) is not free running so this approach cannot be used. The DQS Delay block provides the required clock alignment for DDR memory interfaces.

The DQS signal (selected PIOs only) feeds from the PAD through a DQS delay element to a dedicated DQS routing resource. The DQS signal also feeds the polarity control logic which controls the polarity of the clock to the sync registers in the input register blocks. Figures 2-26 and 2-27 show how the polarity control logic are routed to the PIOs.

The temperature, voltage and process variations of the DQS delay block are compensated by a set of calibration (6-bit bus) signals from two DLLs on opposite sides of the device. Each DLL compensates DQS Delays in its half of the device as shown in Figure 2-27. The DLL loop is compensated for temperature, voltage and process variations by the system clock and feedback loop.

Table 2-9. Characteristics of Normal, Off and Sleep Modes

Characteristic	Normal	Off	Sleep
SLEEPN Pin	High	—	Low
Static I _{cc}	Typical <100mA	0	Typical <100uA
I/O Leakage	<10μA	<1mA	<10μA
Power Supplies VCC/VCCIO/VCCAUX	Normal Range	Off	Normal Range
Logic Operation	User Defined	Non Operational	Non operational
I/O Operation	User Defined	Tri-state	Tri-state
JTAG and Programming circuitry	Operational	Non-operational	Non-operational
EBR Contents and Registers	Maintained	Non-maintained	Non-maintained

SLEEPN Pin Characteristics

The SLEEPN pin behaves as an LVCMOS input with the voltage standard appropriate to the VCC supply for the device. This pin also has a weak pull-up typically in the order of 10μA along with a Schmidt trigger and glitch filter to prevent false triggering. An external pull-up to V_{CC} is recommended when Sleep Mode is not used to ensure the device stays in normal operation mode. Typically the device enters Sleep Mode several hundred ns after SLEEPN is held at a valid low and restarts normal operation as specified in the Sleep Mode Timing table. The AC and DC specifications portion of this data sheet show a detailed timing diagram.

Configuration and Testing

The following section describes the configuration and testing features of the LatticeXP family of devices.

IEEE 1149.1-Compliant Boundary Scan Testability

All LatticeXP devices have boundary scan cells that are accessed through an IEEE 1149.1 compliant test access port (TAP). This allows functional testing of the circuit board, on which the device is mounted, through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port has its own supply voltage V_{CCJ} and can operate with LVCMOS3.3, 2.5, 1.8, 1.5 and 1.2 standards.

For more details on boundary scan test, please see information regarding additional technical documentation at the end of this data sheet.

Device Configuration

All LatticeXP devices contain two possible ports that can be used for device configuration and programming. The test access port (TAP), which supports serial configuration, and the sysCONFIG port that supports both byte-wide and serial configuration.

The non-volatile memory in the LatticeXP can be configured in three different modes:

- In sysCONFIG mode via the sysCONFIG port. Note this can also be done in background mode.
- In 1532 mode via the 1149.1 port.
- In background mode via the 1149.1 port. This allows the device to be operated while reprogramming takes place.

The SRAM configuration memory can be configured in three different ways:

- At power-up via the on-chip non-volatile memory.
- In 1532 mode via the 1149.1 port SRAM direct configuration.
- In sysCONFIG mode via the sysCONFIG port SRAM direct configuration.

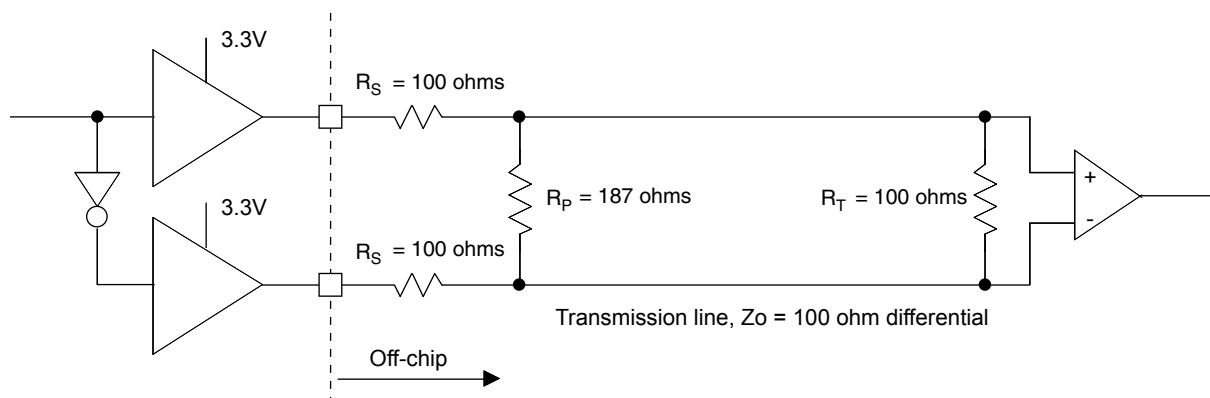
sysIO Single-Ended DC Electrical Characteristics

Input/Output Standard	V_{IL}		V_{IH}		V_{OL} Max. (V)	V_{OH} Min. (V)	I_{OL} (mA)	I_{OH} (mA)
	Min. (V)	Max. (V)	Min. (V)	Max. (V)				
LVCMOS 3.3	-0.3	0.8	2.0	3.6	0.4	$V_{CCIO} - 0.4$	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVTTTL	-0.3	0.8	2.0	3.6	0.4	$V_{CCIO} - 0.4$	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVCMOS 2.5	-0.3	0.7	1.7	3.6	0.4	$V_{CCIO} - 0.4$	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVCMOS 1.8	-0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	3.6	0.4	$V_{CCIO} - 0.4$	16, 12, 8, 4	-16, -12, -8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVCMOS 1.5	-0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	3.6	0.4	$V_{CCIO} - 0.4$	8, 4	-8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVCMOS 1.2 ("C" Version)	-0.3	0.42	0.78	3.6	0.4	$V_{CCIO} - 0.4$	6, 2	-6, -2
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVCMOS 1.2 ("E" Version)	-0.3	$0.35V_{CC}$	$0.65V_{CC}$	3.6	0.4	$V_{CCIO} - 0.4$	6, 2	-6, -2
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
PCI	-0.3	$0.3V_{CCIO}$	$0.5V_{CCIO}$	3.6	$0.1V_{CCIO}$	$0.9V_{CCIO}$	1.5	-0.5
SSTL3 class I	-0.3	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	0.7	$V_{CCIO} - 1.1$	8	-8
SSTL3 class II	-0.3	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	0.5	$V_{CCIO} - 0.9$	16	-16
SSTL2 class I	-0.3	$V_{REF} - 0.18$	$V_{REF} + 0.18$	3.6	0.54	$V_{CCIO} - 0.62$	7.6	-7.6
SSTL2 class II	-0.3	$V_{REF} - 0.18$	$V_{REF} + 0.18$	3.6	0.35	$V_{CCIO} - 0.43$	15.2	-15.2
SSTL18 class I	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	3.6	0.4	$V_{CCIO} - 0.4$	6.7	-6.7
HSTL15 class I	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCIO} - 0.4$	8	-8
HSTL15 class III	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCIO} - 0.4$	24	-8
HSTL18 class I	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCIO} - 0.4$	9.6	-9.6
HSTL18 class II	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCIO} - 0.4$	16	-16
HSTL18 class III	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCIO} - 0.4$	24	-8

1. The average DC current drawn by I/Os between GND connections, or between the last GND in an I/O bank and the end of an I/O bank, as shown in the logic signal connections table shall not exceed $n * 8\text{mA}$. Where n is the number of I/Os between bank GND connections or between the last GND in a bank and the end of a bank.

LVPECL

The LatticeXP devices support differential LVPECL standard. This standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The LVPECL input standard is supported by the LVDS differential input buffer. The scheme shown in Figure 3-3 is one possible solution for point-to-point signals.

Figure 3-3. Differential LVPECL**Table 3-3. LVPECL DC Conditions¹****Over Recommended Operating Conditions**

Symbol	Description	Typical	Units
Z_{OUT}	Output impedance	100	ohms
R_P	Driver parallel resistor	187	ohms
R_S	Driver series resistor	100	ohms
R_T	Receiver termination	100	ohms
V_{OH}	Output high voltage	2.03	V
V_{OL}	Output low voltage	1.27	V
V_{OD}	Output differential voltage	0.76	V
V_{CM}	Output common mode voltage	1.65	V
Z_{BACK}	Back impedance	85.7	ohms
I_{DC}	DC output current	12.7	mA

1. For input buffer, see LVDS table.

For further information on LVPECL, BLVDS and other differential interfaces please see details of additional technical documentation at the end of the data sheet.

RSDS

The LatticeXP devices support differential RSDS standard. This standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The RSDS input standard is supported by the LVDS differential input buffer. The scheme shown in Figure 3-4 is one possible solution for RSDS standard implementation. Use LVDS25E mode with suggested resistors for RSDS operation. Resistor values in Figure 3-4 are industry standard values for 1% resistors.

Derating Logic Timing

Logic timing provided in the following sections of this data sheet and in the ispLEVER design tools are worst case numbers in the operating range. Actual delays at nominal temperature and voltage for best-case process can be much better than the values given in the tables. The ispLEVER design tool from Lattice can provide logic timing numbers at a particular temperature and voltage.

LatticeXP Internal Timing Parameters¹ (Continued)

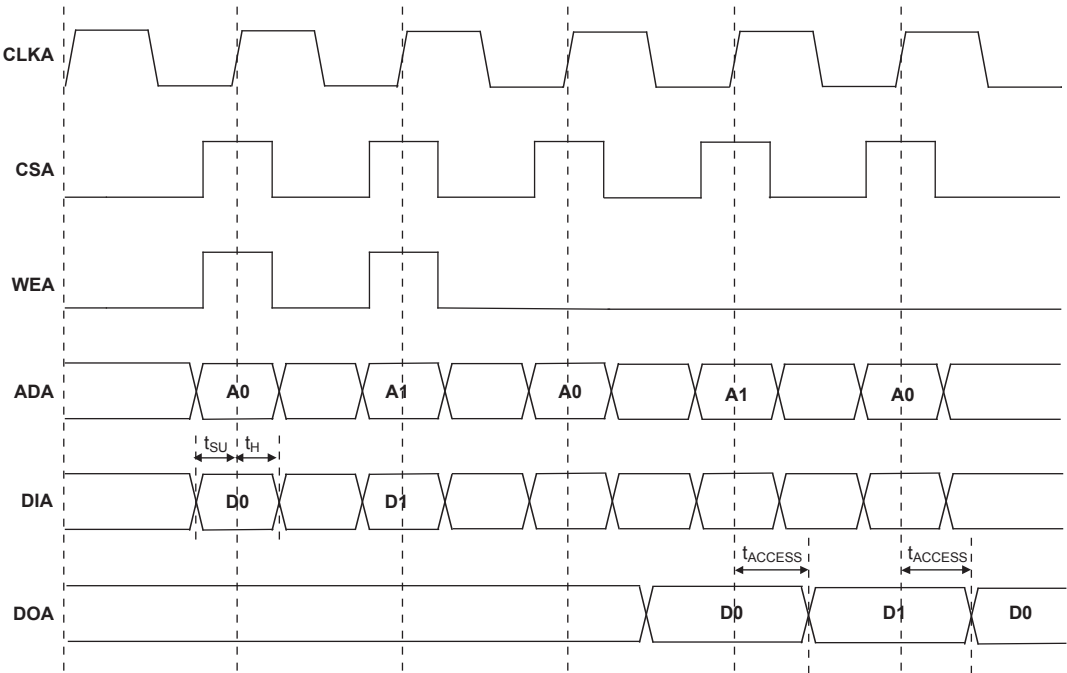
Over Recommended Operating Conditions

Parameter	Description	-5		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t_{RSTO_EBR}	Reset To Output Delay Time from EBR Output Register	—	1.61	—	1.94	—	2.32	ns
PLL Parameters								
t_{RSTREC}	Reset Recovery to Rising Clock	1.00	—	1.00	—	1.00	—	ns
t_{RSTSU}	Reset Signal Setup Time	1.00	—	1.00	—	1.00	—	ns

1. Internal parameters are characterized but not tested on every device.
Timing v.F0.11

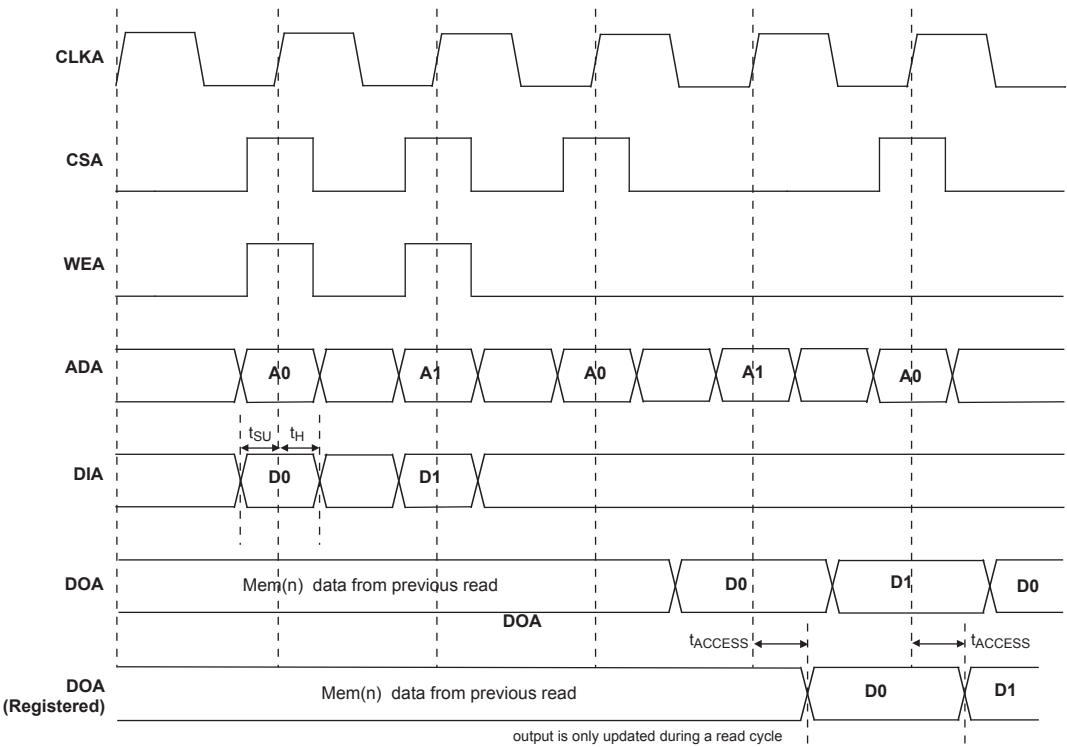
EBR Memory Timing Diagrams

Figure 3-8. Read Mode (Normal)



Note: Input data and address are registered at the positive edge of the clock and output data appears after the positive of the clock.

Figure 3-9. Read Mode with Input and Output Registers



LFXP3 Logic Signal Connections: 100 TQFP (Cont.)

Pin Number	Pin Function	Bank	Differential	Dual Function
88	PT14B	1	-	D7
89	PT13B	0	C	BUSY
90	GNDIO0	0	-	-
91	PT13A	0	T	CS1N
92	PT12B	0	C	PCLKC0_0
93	PT12A	0	T	PCLKT0_0
94	VCCIO0	0	-	-
95	PT9A	0	-	DOUT
96	PT8A	0	-	WRITEN
97	PT6A	0	-	DI
98	PT5A	0	-	CSN
99	GND	-	-	-
100	CFG0	0	-	-

1. Applies to LFXP "C" only.

2. Applies to LFXP "E" only.

3. Supports dedicated LVDS outputs.

LFXP6 & LFXP10 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFXP6				LFXP10			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
E16	TDO	-	-	-	TDO	-	-	-
D16	VCCJ	-	-	-	VCCJ	-	-	-
D14	TDI	-	-	-	TDI	-	-	-
C14	TMS	-	-	-	TMS	-	-	-
B14	TCK	-	-	-	TCK	-	-	-
-	GNDIO1	1	-	-	GNDIO1	1	-	-
A15	PT31B	1	C	-	PT35B	1	C	-
B15	PT31A	1	T	-	PT35A	1	T	-
-	GNDIO1	1	-	-	GNDIO1	1	-	-
D12	PT28A	1	-	VREF1_1	PT34B	1	C	VREF1_1
C11	PT30A	1	T	DQS	PT34A	1	T	DQS
A14	PT29B	1	-	-	PT33B	1	-	-
B13	PT30B	1	C	-	PT32A	1	-	-
F12	PT27B	1	C	-	PT31B	1	C	-
E11	PT27A	1	T	-	PT31A	1	T	-
A13	PT26B	1	C	-	PT30B	1	C	-
C13	PT26A	1	T	D0	PT30A	1	T	D0
-	GNDIO1	1	-	-	GNDIO1	1	-	-
C10	PT25B	1	C	D1	PT29B	1	C	D1
E10	PT25A	1	T	VREF2_1	PT29A	1	T	VREF2_1
A12	PT24B	1	C	-	PT28B	1	C	-
B12	PT24A	1	T	D2	PT28A	1	T	D2
C12	PT23B	1	C	D3	PT27B	1	C	D3
A11	PT23A	1	T	-	PT27A	1	T	-
B11	PT22B	1	C	-	PT26B	1	C	-
D11	PT22A	1	T	DQS	PT26A	1	T	DQS
-	GNDIO1	1	-	-	GNDIO1	1	-	-
B9	PT21B	1	-	-	PT25B	1	-	-
D9	PT20A	1	-	D4	PT24A	1	-	D4
A10	PT19B	1	C	-	PT23B	1	C	-
B10	PT19A	1	T	D5	PT23A	1	T	D5
D10	PT18B	1	C	D6	PT22B	1	C	D6
A9	PT18A	1	T	-	PT22A	1	T	-
C9	PT17B	1	C	D7	PT21B	1	C	D7
C8	PT17A	1	T	-	PT21A	1	T	-
E9	PT16B	0	C	BUSY	PT20B	0	C	BUSY
-	GNDIO0	0	-	-	GNDIO0	0	-	-
B8	PT16A	0	T	CS1N	PT20A	0	T	CS1N
A8	PT15B	0	C	PCLKC0_0	PT19B	0	C	PCLKC0_0
A7	PT15A	0	T	PCLKT0_0	PT19A	0	T	PCLKT0_0
B7	PT14B	0	C	-	PT18B	0	C	-
C7	PT14A	0	T	DQS	PT18A	0	T	DQS

LFXP15 & LFXP20 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
P16	PR37B	3	C ³	-	PR41B	3	C ³	-
R16	PR37A	3	T ³	DQS	PR41A	3	T ³	DQS
M15	PR36B	3	-	-	PR40B	3	-	-
N14	PR35A	3	-	VREF1_3	PR39A	3	-	VREF1_3
-	GNDIO3	3	-	-	GNDIO3	3	-	-
M14	PR33B	3	C	-	PR37B	3	C	-
L13	PR33A	3	T	-	PR37A	3	T	-
L15	PR32B	3	C ³	-	PR36B	3	C ³	-
L14	PR32A	3	T ³	-	PR36A	3	T ³	-
L12	PR30A	3	-	-	PR34A	3	-	-
M16	PR29B	3	C	RLM0_PLLC_IN_A	PR33B	3	C	RLM0_PLLC_IN_A
N16	PR29A	3	T	RLM0_PLLT_IN_A	PR33A	3	T	RLM0_PLLT_IN_A
-	GNDIO3	3	-	-	GNDIO3	3	-	-
K14	PR28B	3	C ³	-	PR32B	3	C ³	-
K15	PR28A	3	T ³	DQS	PR32A	3	T ³	DQS
K12	PR27B	3	-	-	PR31B	3	-	-
K13	PR26A	3	-	VREF2_3	PR30A	3	-	VREF2_3
L16	PR25B	3	C ³	-	PR29B	3	C ³	-
K16	PR25A	3	T ³	-	PR29A	3	T ³	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
J15	PR23B	3	C ³	-	PR27B	3	C ³	-
J14	PR23A	3	T ³	-	PR27A	3	T ³	-
J13	GNDP1	-	-	-	GNDP1	-	-	-
J12	VCCP1	-	-	-	VCCP1	-	-	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-
J16	PR21B	2	C	PCLKC2_0	PR21B	2	C	PCLKC2_0
H16	PR21A	2	T	PCLKT2_0	PR21A	2	T	PCLKT2_0
H13	PR20B	2	C ³	-	PR20B	2	C ³	-
H12	PR20A	2	T ³	DQS	PR20A	2	T ³	DQS
H15	PR19B	2	-	-	PR19B	2	-	-
H14	PR18A	2	-	VREF1_2	PR18A	2	-	VREF1_2
-	GNDIO2	2	-	-	GNDIO2	2	-	-
G15	PR17B	2	C ³	-	PR17B	2	C ³	-
G14	PR17A	2	T ³	-	PR17A	2	T ³	-
G16	PR16B	2	C	RUM0_PLLC_IN_A	PR16B	2	C	RUM0_PLLC_IN_A
F16	PR16A	2	T	RUM0_PLLT_IN_A	PR16A	2	T	RUM0_PLLT_IN_A
G13	PR15B	2	-	-	PR15B	2	-	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-
G12	PR12B	2	C	-	PR12B	2	C	-
F13	PR12A	2	T	-	PR12A	2	T	-
B16	PR11B	2	C ³	-	PR11B	2	C ³	-
C16	PR11A	2	T ³	DQS	PR11A	2	T ³	DQS

LFXP10, LFXP15 & LFXP20 Logic Signal Connections: 388 fpBGA (Cont.)

Ball Number	LFXP10				LFXP15				LFXP20			
	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function
A7	PT13A	0	T	DI	PT18A	0	T	DI	PT22A	0	T	DI
B7	PT12B	0	C	-	PT17B	0	C	-	PT21B	0	C	-
C6	PT12A	0	T	CSN	PT17A	0	T	CSN	PT21A	0	T	CSN
C10	PT11B	0	C	-	PT16B	0	C	-	PT20B	0	C	-
C9	PT11A	0	T	-	PT16A	0	T	-	PT20A	0	T	-
A6	PT10B	0	C	VREF2_0	PT15B	0	C	VREF2_0	PT19B	0	C	VREF2_0
B6	PT10A	0	T	DQS	PT15A	0	T	DQS	PT19A	0	T	DQS
A5	PT9B	0	-	-	PT14B	0	-	-	PT18B	0	-	-
B5	PT8A	0	-	-	PT13A	0	-	-	PT17A	0	-	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-	GNDIO0	0	-	-
C5	PT7B	0	C	-	PT12B	0	C	-	PT16B	0	C	-
A4	PT7A	0	T	-	PT12A	0	T	-	PT16A	0	T	-
D9	PT6B	0	C	-	PT11B	0	C	-	PT15B	0	C	-
D8	PT6A	0	T	-	PT11A	0	T	-	PT15A	0	T	-
B4	PT5B	0	C	-	PT10B	0	C	-	PT14B	0	C	-
A2	PT5A	0	T	-	PT10A	0	T	-	PT14A	0	T	-
A3	PT4B	0	C	-	PT9B	0	C	-	PT13B	0	C	-
B3	PT4A	0	T	-	PT9A	0	T	-	PT13A	0	T	-
C4	PT3B	0	C	-	PT8B	0	C	-	PT12B	0	C	-
C3	PT3A	0	T	-	PT8A	0	T	-	PT12A	0	T	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-	GNDIO0	0	-	-
C2	-	-	-	-	PT7B	0	C	-	PT11B	0	C	-
D3	PT2A	0	-	-	PT7A	0	T	DQS	PT11A	0	T	DQS
D7	-	-	-	-	PT6B	0	-	-	PT10B	0	-	-
D6	-	-	-	-	PT5A	0	-	-	PT9A	0	-	-
E4	-	-	-	-	PT4B	0	C	-	PT8B	0	C	-
D4	-	-	-	-	PT4A	0	T	-	PT8A	0	T	-
D5	-	-	-	-	PT3B	0	-	-	PT7B	0	-	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-	GNDIO0	0	-	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-	GNDIO0	0	-	-
C1	CFG0	0	-	-	CFG0	0	-	-	CFG0	0	-	-
B2	CFG1	0	-	-	CFG1	0	-	-	CFG1	0	-	-
B1	DONE	0	-	-	DONE	0	-	-	DONE	0	-	-
A1	GND	-	-	-	GND	-	-	-	GND	-	-	-
A22	GND	-	-	-	GND	-	-	-	GND	-	-	-
AB1	GND	-	-	-	GND	-	-	-	GND	-	-	-
AB22	GND	-	-	-	GND	-	-	-	GND	-	-	-
H10	GND	-	-	-	GND	-	-	-	GND	-	-	-
H11	GND	-	-	-	GND	-	-	-	GND	-	-	-
H12	GND	-	-	-	GND	-	-	-	GND	-	-	-
H13	GND	-	-	-	GND	-	-	-	GND	-	-	-
H14	GND	-	-	-	GND	-	-	-	GND	-	-	-
J10	GND	-	-	-	GND	-	-	-	GND	-	-	-
J11	GND	-	-	-	GND	-	-	-	GND	-	-	-
J12	GND	-	-	-	GND	-	-	-	GND	-	-	-
J13	GND	-	-	-	GND	-	-	-	GND	-	-	-
J14	GND	-	-	-	GND	-	-	-	GND	-	-	-
J9	GND	-	-	-	GND	-	-	-	GND	-	-	-
K10	GND	-	-	-	GND	-	-	-	GND	-	-	-

LFXP10, LFXP15 & LFXP20 Logic Signal Connections: 388 fpBGA (Cont.)

Ball Number	LFXP10				LFXP15				LFXP20			
	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function
G7	VCCAUX	-	-	-	VCCAUX	-	-	-	VCCAUX	-	-	-
T16	VCCAUX	-	-	-	VCCAUX	-	-	-	VCCAUX	-	-	-
T7	VCCAUX	-	-	-	VCCAUX	-	-	-	VCCAUX	-	-	-
G10	VCCIO0	0	-	-	VCCIO0	0	-	-	VCCIO0	0	-	-
G11	VCCIO0	0	-	-	VCCIO0	0	-	-	VCCIO0	0	-	-
G8	VCCIO0	0	-	-	VCCIO0	0	-	-	VCCIO0	0	-	-
G9	VCCIO0	0	-	-	VCCIO0	0	-	-	VCCIO0	0	-	-
H8	VCCIO0	0	-	-	VCCIO0	0	-	-	VCCIO0	0	-	-
G12	VCCIO1	1	-	-	VCCIO1	1	-	-	VCCIO1	1	-	-
G13	VCCIO1	1	-	-	VCCIO1	1	-	-	VCCIO1	1	-	-
G14	VCCIO1	1	-	-	VCCIO1	1	-	-	VCCIO1	1	-	-
G15	VCCIO1	1	-	-	VCCIO1	1	-	-	VCCIO1	1	-	-
H15	VCCIO1	1	-	-	VCCIO1	1	-	-	VCCIO1	1	-	-
H16	VCCIO2	2	-	-	VCCIO2	2	-	-	VCCIO2	2	-	-
J16	VCCIO2	2	-	-	VCCIO2	2	-	-	VCCIO2	2	-	-
K16	VCCIO2	2	-	-	VCCIO2	2	-	-	VCCIO2	2	-	-
L16	VCCIO2	2	-	-	VCCIO2	2	-	-	VCCIO2	2	-	-
M16	VCCIO3	3	-	-	VCCIO3	3	-	-	VCCIO3	3	-	-
N16	VCCIO3	3	-	-	VCCIO3	3	-	-	VCCIO3	3	-	-
P16	VCCIO3	3	-	-	VCCIO3	3	-	-	VCCIO3	3	-	-
R16	VCCIO3	3	-	-	VCCIO3	3	-	-	VCCIO3	3	-	-
R15	VCCIO4	4	-	-	VCCIO4	4	-	-	VCCIO4	4	-	-
T12	VCCIO4	4	-	-	VCCIO4	4	-	-	VCCIO4	4	-	-
T13	VCCIO4	4	-	-	VCCIO4	4	-	-	VCCIO4	4	-	-
T14	VCCIO4	4	-	-	VCCIO4	4	-	-	VCCIO4	4	-	-
T15	VCCIO4	4	-	-	VCCIO4	4	-	-	VCCIO4	4	-	-
R8	VCCIO5	5	-	-	VCCIO5	5	-	-	VCCIO5	5	-	-
T10	VCCIO5	5	-	-	VCCIO5	5	-	-	VCCIO5	5	-	-
T11	VCCIO5	5	-	-	VCCIO5	5	-	-	VCCIO5	5	-	-
T8	VCCIO5	5	-	-	VCCIO5	5	-	-	VCCIO5	5	-	-
T9	VCCIO5	5	-	-	VCCIO5	5	-	-	VCCIO5	5	-	-
M7	VCCIO6	6	-	-	VCCIO6	6	-	-	VCCIO6	6	-	-
N7	VCCIO6	6	-	-	VCCIO6	6	-	-	VCCIO6	6	-	-
P7	VCCIO6	6	-	-	VCCIO6	6	-	-	VCCIO6	6	-	-
R7	VCCIO6	6	-	-	VCCIO6	6	-	-	VCCIO6	6	-	-
H7	VCCIO7	7	-	-	VCCIO7	7	-	-	VCCIO7	7	-	-
J7	VCCIO7	7	-	-	VCCIO7	7	-	-	VCCIO7	7	-	-
K7	VCCIO7	7	-	-	VCCIO7	7	-	-	VCCIO7	7	-	-
L7	VCCIO7	7	-	-	VCCIO7	7	-	-	VCCIO7	7	-	-

1. Applies to LFXP "C" only.
2. Applies to LFXP "E" only.
3. Supports dedicated LVDS outputs.

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
F5	PROGRAMN	7	-	-	PROGRAMN	7	-	-
E3	CCLK	7	-	-	CCLK	7	-	-
C1	PL2B	7	-	-	PL2B	7	-	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-
G5	PL3A	7	T ³	-	PL3A	7	T ³	-
G6	PL3B	7	C ³	-	PL3B	7	C ³	-
F4	PL4A	7	T	-	PL4A	7	T	-
F3	PL4B	7	C	-	PL4B	7	C	-
G4	PL5A	7	T ³	-	PL5A	7	T ³	-
G3	PL5B	7	C ³	-	PL5B	7	C ³	-
D1	PL6A	7	T ³	-	PL6A	7	T ³	-
D2	PL6B	7	C ³	-	PL6B	7	C ³	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-
E1	PL7A	7	T	LUM0_PLLT_FB_A	PL7A	7	T	LUM0_PLLT_FB_A
E2	PL7B	7	C	LUM0_PLLC_FB_A	PL7B	7	C	LUM0_PLLC_FB_A
H5	PL8A	7	T ³	-	PL8A	7	T ³	-
H6	PL8B	7	C ³	-	PL8B	7	C ³	-
H4	PL9A	7	-	-	PL9A	7	-	-
H3	PL10B	7	-	VREF1_7	PL10B	7	-	VREF1_7
F1	PL11A	7	T ³	DQS	PL11A	7	T ³	DQS
F2	PL11B	7	C ³	-	PL11B	7	C ³	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-
J5	PL12A	7	T	-	PL12A	7	T	-
J6	PL12B	7	C	-	PL12B	7	C	-
G1	PL13A	7	T ³	-	PL13A	7	T ³	-
G2	PL13B	7	C ³	-	PL13B	7	C ³	-
J4	PL15A	7	T ³	-	PL15A	7	T ³	-
J3	PL15B	7	C ³	-	PL15B	7	C ³	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-
H1	PL16A	7	T	LUM0_PLLT_IN_A	PL16A	7	T	LUM0_PLLT_IN_A
H2	PL16B	7	C	LUM0_PLLC_IN_A	PL16B	7	C	LUM0_PLLC_IN_A
J1	PL17A	7	T ³	-	PL17A	7	T ³	-
J2	PL17B	7	C ³	-	PL17B	7	C ³	-
K3	PL18A	7	-	VREF2_7	PL18A	7	-	VREF2_7
K2	PL19B	7	-	-	PL19B	7	-	-
K4	PL20A	7	T ³	DQS	PL20A	7	T ³	DQS
-	GNDIO7	7	-	-	GNDIO7	7	-	-
K5	PL20B	7	C ³	-	PL20B	7	C ³	-
K1	PL21A	7	T	-	PL21A	7	T	-
L2	PL21B	7	C	-	PL21B	7	C	-
L4	PL22A	7	T ³	-	PL22A	7	T ³	-
L3	PL22B	7	C ³	-	PL22B	7	C ³	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
AB19	PB37A	4	-	-	PB41A	4	-	-
AB20	PB38B	4	-	-	PB42B	4	-	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
V15	PB39A	4	T	DQS	PB43A	4	T	DQS
U15	PB39B	4	C	-	PB43B	4	C	-
Y15	PB40A	4	T	-	PB44A	4	T	-
W15	PB40B	4	C	-	PB44B	4	C	-
AA16	PB41A	4	T	-	PB45A	4	T	-
AA17	PB41B	4	C	-	PB45B	4	C	-
AA18	PB42A	4	T	-	PB46A	4	T	-
AA19	PB42B	4	C	-	PB46B	4	C	-
Y16	PB43A	4	T	-	PB47A	4	T	-
W16	PB43B	4	C	-	PB47B	4	C	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
AA20	PB44A	4	T	-	PB48A	4	T	-
AA21	PB44B	4	C	-	PB48B	4	C	-
Y17	PB45A	4	-	-	PB49A	4	-	-
Y18	PB46B	4	-	-	PB50B	4	-	-
Y19	PB47A	4	T	DQS	PB51A	4	T	DQS
Y20	PB47B	4	C	-	PB51B	4	C	-
V16	PB48A	4	T	-	PB52A	4	T	-
U16	PB48B	4	C	-	PB52B	4	C	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
U18	-	-	-	-	PB53A	4	T	-
V18	-	-	-	-	PB53B	4	C	-
W19	-	-	-	-	PB54A	4	T	-
W18	-	-	-	-	PB54B	4	C	-
U17	-	-	-	-	PB55A	4	T	-
V17	-	-	-	-	PB55B	4	C	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
W17	-	-	-	-	PB56A	4	-	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
V19	PR43A	3	-	-	PR47A	3	-	-
U20	PR42B	3	C ³	-	PR46B	3	C ³	-
U19	PR42A	3	T ³	-	PR46A	3	T ³	-
V20	PR41B	3	C	-	PR45B	3	C	-
W20	PR41A	3	T	-	PR45A	3	T	-
T17	PR40B	3	C ³	-	PR44B	3	C ³	-
T18	PR40A	3	T ³	-	PR44A	3	T ³	-
T19	PR39B	3	C ³	-	PR43B	3	C ³	-
T20	PR39A	3	T ³	-	PR43A	3	T ³	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
J21	PR20B	2	C ³	-	PR20B	2	C ³	-
J22	PR20A	2	T ³	DQS	PR20A	2	T ³	DQS
K18	PR19B	2	-	-	PR19B	2	-	-
K19	PR18A	2	-	VREF1_2	PR18A	2	-	VREF1_2
-	GNDIO2	2	-	-	GNDIO2	2	-	-
K21	PR17B	2	C ³	-	PR17B	2	C ³	-
K20	PR17A	2	T ³	-	PR17A	2	T ³	-
H21	PR16B	2	C	RUM0_PLLC_IN_A	PR16B	2	C	RUM0_PLLC_IN_A
H22	PR16A	2	T	RUM0_PLLT_IN_A	PR16A	2	T	RUM0_PLLT_IN_A
J20	PR15B	2	C ³	-	PR15B	2	C ³	-
J19	PR15A	2	T ³	-	PR15A	2	T ³	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-
J17	PR13B	2	C ³	-	PR13B	2	C ³	-
J18	PR13A	2	T ³	-	PR13A	2	T ³	-
G21	PR12B	2	C	-	PR12B	2	C	-
G22	PR12A	2	T	-	PR12A	2	T	-
F21	PR11B	2	C ³	-	PR11B	2	C ³	-
F22	PR11A	2	T ³	DQS	PR11A	2	T ³	DQS
-	GNDIO2	2	-	-	GNDIO2	2	-	-
H20	PR10B	2	-	-	PR10B	2	-	-
H19	PR9A	2	-	VREF2_2	PR9A	2	-	VREF2_2
H17	PR8B	2	C ³	-	PR8B	2	C ³	-
H18	PR8A	2	T ³	-	PR8A	2	T ³	-
E21	PR7B	2	C	RUM0_PLLC_FB_A	PR7B	2	C	RUM0_PLLC_FB_A
E22	PR7A	2	T	RUM0_PLLT_FB_A	PR7A	2	T	RUM0_PLLT_FB_A
D21	PR6B	2	C ³	-	PR6B	2	C ³	-
D22	PR6A	2	T ³	-	PR6A	2	T ³	-
G20	PR5B	2	C ³	-	PR5B	2	C ³	-
G19	PR5A	2	T ³	-	PR5A	2	T ³	-
G17	PR4B	2	C	-	PR4B	2	C	-
G18	PR4A	2	T	-	PR4A	2	T	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-
F18	PR3B	2	C ³	-	PR3B	2	C ³	-
F19	PR3A	2	T ³	-	PR3A	2	T ³	-
C22	PR2B	2	-	-	PR2B	2	-	-
F20	TDO	-	-	-	TDO	-	-	-
E20	VCCJ	-	-	-	VCCJ	-	-	-
D19	TDI	-	-	-	TDI	-	-	-
E19	TMS	-	-	-	TMS	-	-	-
D20	TCK	-	-	-	TCK	-	-	-
C20	-	-	-	-	PT56A	1	-	-
-	GNDIO1	1	-	-	GNDIO1	1	-	-

Thermal Management

Thermal management is recommended as part of any sound FPGA design methodology. To assess the thermal characteristics of a system, Lattice specifies a maximum allowable junction temperature in all device data sheets. Designers must complete a thermal analysis of their specific design to ensure that the device and package do not exceed the junction temperature limits. Refer to the Thermal Management document to find the device/package specific thermal values.

For Further Information

For further information regarding Thermal Management, refer to the following located on the Lattice website at www.latticesemi.com.

- Thermal Management document
- Technical Note TN1052 - Power Estimation and Management for LatticeECP/EC and LatticeXP Devices
- Power Calculator tool included with Lattice's ispLEVER design tool, or as a standalone download from www.latticesemi.com/software

Commercial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP15E-3FN484C	300	1.2V	-3	fpBGA	484	COM	15.5K
LFXP15E-4FN484C	300	1.2V	-4	fpBGA	484	COM	15.5K
LFXP15E-5FN484C	300	1.2V	-5	fpBGA	484	COM	15.5K
LFXP15E-3FN388C	268	1.2V	-3	fpBGA	388	COM	15.5K
LFXP15E-4FN388C	268	1.2V	-4	fpBGA	388	COM	15.5K
LFXP15E-5FN388C	268	1.2V	-5	fpBGA	388	COM	15.5K
LFXP15E-3FN256C	188	1.2V	-3	fpBGA	256	COM	15.5K
LFXP15E-4FN256C	188	1.2V	-4	fpBGA	256	COM	15.5K
LFXP15E-5FN256C	188	1.2V	-5	fpBGA	256	COM	15.5K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20E-3FN484C	340	1.2V	-3	fpBGA	484	COM	19.7K
LFXP20E-4FN484C	340	1.2V	-4	fpBGA	484	COM	19.7K
LFXP20E-5FN484C	340	1.2V	-5	fpBGA	484	COM	19.7K
LFXP20E-3FN388C	268	1.2V	-3	fpBGA	388	COM	19.7K
LFXP20E-4FN388C	268	1.2V	-4	fpBGA	388	COM	19.7K
LFXP20E-5FN388C	268	1.2V	-5	fpBGA	388	COM	19.7K
LFXP20E-3FN256C	188	1.2V	-3	fpBGA	256	COM	19.7K
LFXP20E-4FN256C	188	1.2V	-4	fpBGA	256	COM	19.7K
LFXP20E-5FN256C	188	1.2V	-5	fpBGA	256	COM	19.7K

Industrial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP3C-3QN208I	136	1.8/2.5/3.3V	-3	PQFP	208	IND	3.1K
LFXP3C-4QN208I	136	1.8/2.5/3.3V	-4	PQFP	208	IND	3.1K
LFXP3C-3TN144I	100	1.8/2.5/3.3V	-3	TQFP	144	IND	3.1K
LFXP3C-4TN144I	100	1.8/2.5/3.3V	-4	TQFP	144	IND	3.1K
LFXP3C-3TN100I	62	1.8/2.5/3.3V	-3	TQFP	100	IND	3.1K
LFXP3C-4TN100I	62	1.8/2.5/3.3V	-4	TQFP	100	IND	3.1K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP6C-3FN256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	5.8K
LFXP6C-4FN256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	5.8K
LFXP6C-3QN208I	142	1.8/2.5/3.3V	-3	PQFP	208	IND	5.8K
LFXP6C-4QN208I	142	1.8/2.5/3.3V	-4	PQFP	208	IND	5.8K
LFXP6C-3TN144I	100	1.8/2.5/3.3V	-3	TQFP	144	IND	5.8K
LFXP6C-4TN144I	100	1.8/2.5/3.3V	-4	TQFP	144	IND	5.8K

Industrial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP10C-3FN388I	244	1.8/2.5/3.3V	-3	fpBGA	388	IND	9.7K
LFXP10C-4FN388I	244	1.8/2.5/3.3V	-4	fpBGA	388	IND	9.7K
LFXP10C-3FN256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	9.7K
LFXP10C-4FN256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	9.7K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP15C-3FN484I	300	1.8/2.5/3.3V	-3	fpBGA	484	IND	15.5K
LFXP15C-4FN484I	300	1.8/2.5/3.3V	-4	fpBGA	484	IND	15.5K
LFXP15C-3FN388I	268	1.8/2.5/3.3V	-3	fpBGA	388	IND	15.5K
LFXP15C-4FN388I	268	1.8/2.5/3.3V	-4	fpBGA	388	IND	15.5K
LFXP15C-3FN256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	15.5K
LFXP15C-4FN256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	15.5K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20C-3FN484I	340	1.8/2.5/3.3V	-3	fpBGA	484	IND	19.7K
LFXP20C-4FN484I	340	1.8/2.5/3.3V	-4	fpBGA	484	IND	19.7K
LFXP20C-3FN388I	268	1.8/2.5/3.3V	-3	fpBGA	388	IND	19.7K
LFXP20C-4FN388I	268	1.8/2.5/3.3V	-4	fpBGA	388	IND	19.7K
LFXP20C-3FN256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	19.7K
LFXP20C-4FN256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	19.7K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP3E-3QN208I	136	1.2V	-3	PQFP	208	IND	3.1K
LFXP3E-4QN208I	136	1.2V	-4	PQFP	208	IND	3.1K
LFXP3E-3TN144I	100	1.2V	-3	TQFP	144	IND	3.1K
LFXP3E-4TN144I	100	1.2V	-4	TQFP	144	IND	3.1K
LFXP3E-3TN100I	62	1.2V	-3	TQFP	100	IND	3.1K
LFXP3E-4TN100I	62	1.2V	-4	TQFP	100	IND	3.1K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP6E-3FN256I	188	1.2V	-3	fpBGA	256	IND	5.8K
LFXP6E-4FN256I	188	1.2V	-4	fpBGA	256	IND	5.8K
LFXP6E-3QN208I	142	1.2V	-3	PQFP	208	IND	5.8K
LFXP6E-4QN208I	142	1.2V	-4	PQFP	208	IND	5.8K
LFXP6E-3TN144I	100	1.2V	-3	TQFP	144	IND	5.8K
LFXP6E-4TN144I	100	1.2V	-4	TQFP	144	IND	5.8K